

Features

- Advanced Trench MOS Technology
- Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available

Product Summary

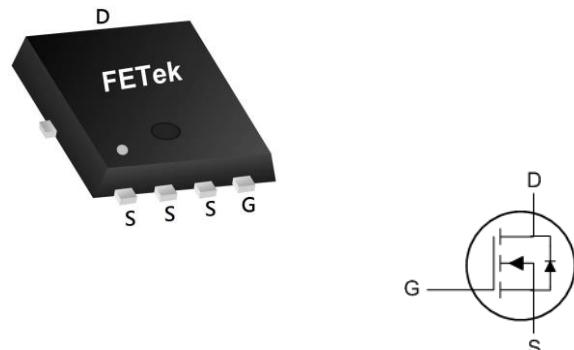


BVDSS	RDS(ON)	ID
60V	12mΩ	33A

Application

- Motor Control.
- DC/DC Converter.
- Synchronous rectifier applications.

PRPAK5x6 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	60	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	33	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	21	A
I _{DM}	Pulsed Drain Current ²	100	A
EAS	Single Pulse Avalanche Energy ³	54	mJ
I _{AS}	Avalanche Current	33	A
P _D @T _C =25°C	Total Power Dissipation ⁴	21	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	60	°C/W
R _{θJC}	Thermal Resistance Junction-case ¹	---	6	°C/W



FETek Technology Corp.

FKBA6054

N-Ch 60V Fast Switching MOSFETs

Electrical Characteristics ($T_J=25^\circ C$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=12A$	---	8	12	$m\Omega$
		$V_{GS}=4.5V, I_D=12A$	---	13	18	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	2	2.3	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=48V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	μA
		$V_{DS}=48V, V_{GS}=0V, T_J=55^\circ C$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	1.0	---	Ω
Q_g	Total Gate Charge (10V)	$V_{DS}=30V, V_{GS}=10V, I_D=12A$	---	15.8	---	nC
Q_g	Total Gate Charge (4.5V)		---	8.7	---	
Q_{gs}	Gate-Source Charge		---	3.1	---	
Q_{gd}	Gate-Drain Charge		---	4.4	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=30V, V_{GS}=10V, R_G=3.3\Omega, I_D=12A$	---	5.8	---	ns
T_r	Rise Time		---	3.5	---	
$T_{d(off)}$	Turn-Off Delay Time		---	26	---	
T_f	Fall Time		---	3.2	---	
C_{iss}	Input Capacitance	$V_{DS}=30V, V_{GS}=0V, f=1MHz$	---	760	---	pF
C_{oss}	Output Capacitance		---	272	---	
C_{rss}	Reverse Transfer Capacitance		---	26	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Current	---	---	33	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	---	1.2	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. Single pulse width limited by junction temperature $T_{J(MAX)}=150^\circ C$.
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=33A$
- 4.The power dissipation is limited by $150^\circ C$ junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

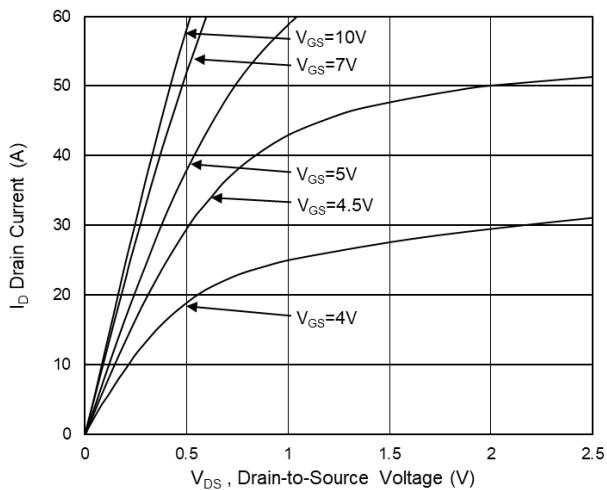


Fig.1 Typical Output Characteristics

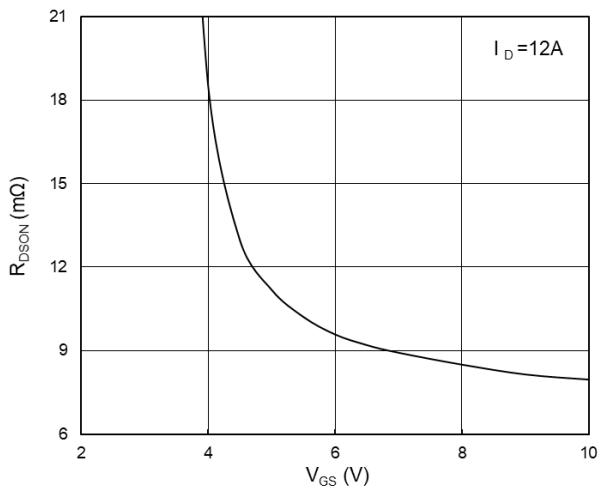


Fig.2 On-Resistance vs G-S Voltage

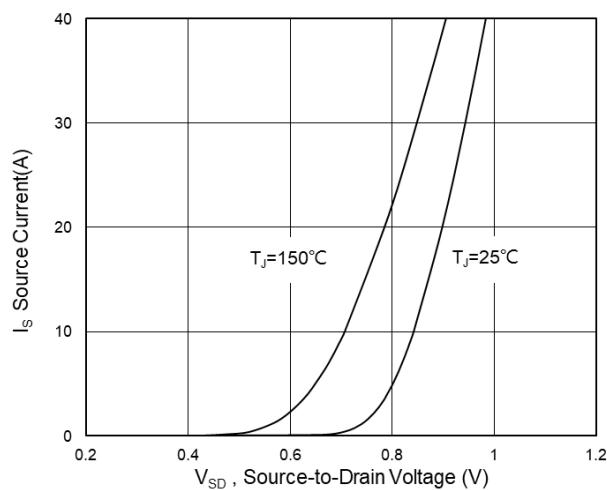


Fig.3 Source Drain Forward Characteristics

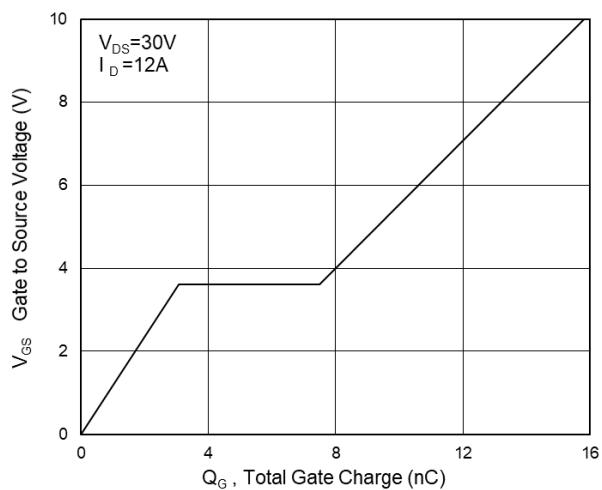


Fig.4 Gate-Charge Characteristics

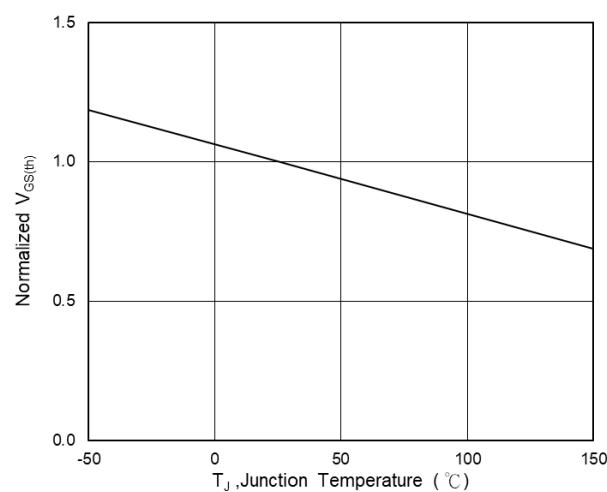


Fig.5 Normalized $V_{GS(th)}$ vs T_J

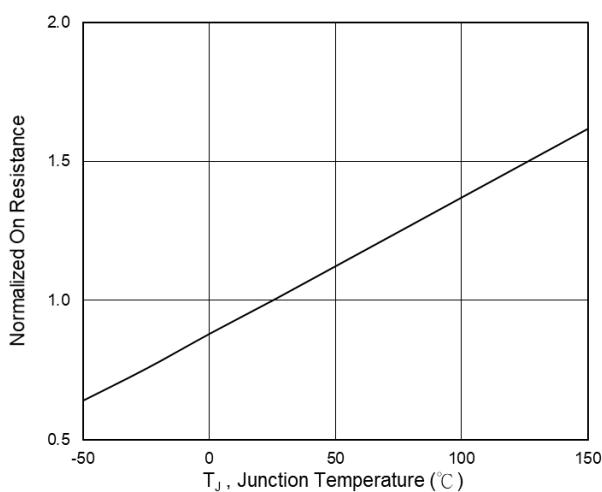
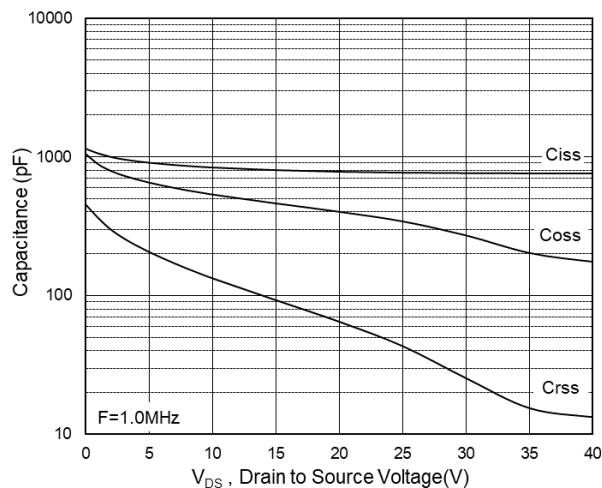
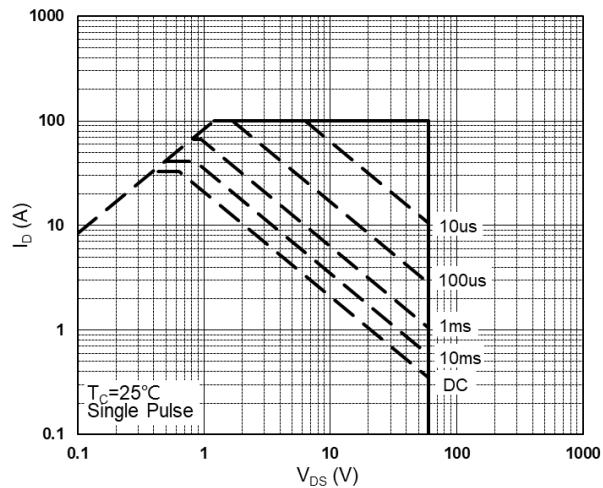
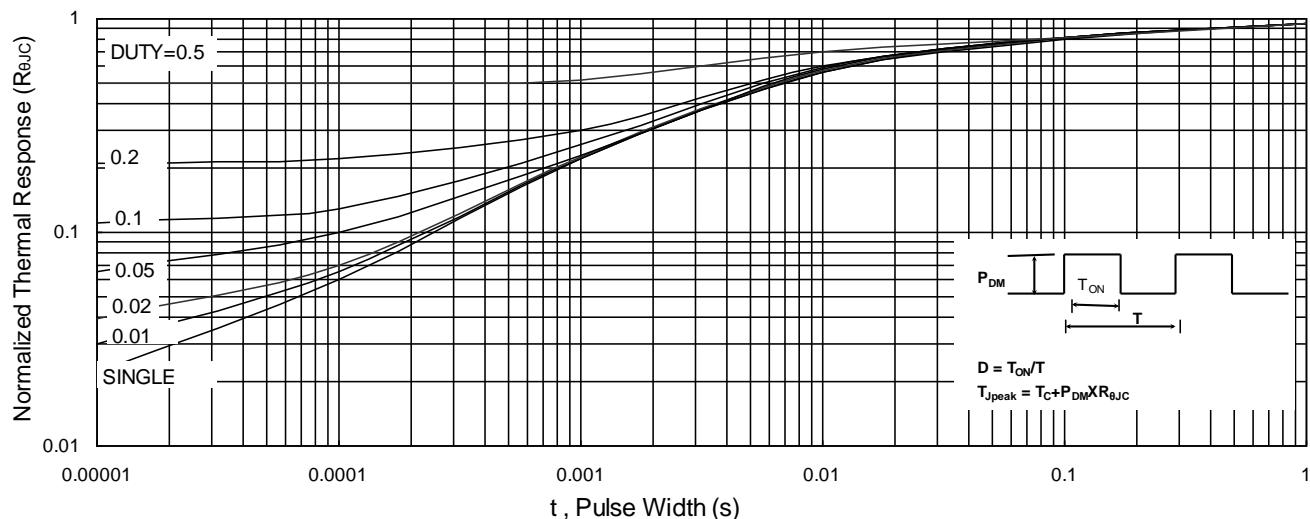
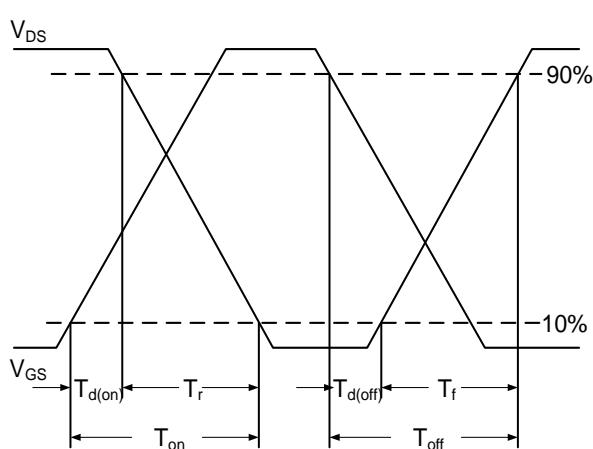
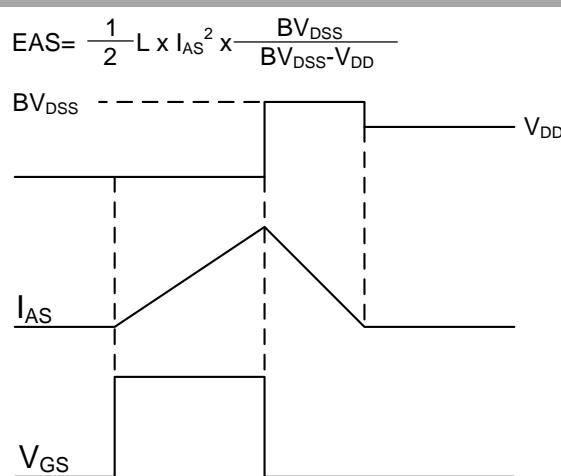


Fig.6 Normalized $R_{DS(on)}$ vs T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform